

METHOD FOR BACKSIDE ALIGNMENT OF PHOTO-PROCESSES USING STANDARD FRONT SIDE ALIGNMENT TOOLS

Abstract

An image of an integrated circuit chip and optical kerf and their mirror image are formed within a single optical field. When a substrate pattern using this process is flipped over or reversed, the processed pattern appears the same as on the first side, equal to its own mirror image. Prior to the backside lithography, a portion of the second side is removed to allow detection of alignment marks on the first side from the second side of the substrate. Once the alignment marks are detected, the lithography continues as though the substrate was not flipped over at all.